Solder paste SB58-COSMO-NH-T4 DISPENSER

GENMA EUROPE

Product description

GENMA solder paste – our proven COSMO solder paste is now available with a low temperature alloy air bubble free for dispensing. The SB58-COSMO-NH-T4 is a low-temperature solder paste. Because of the low melting point it is used in areas where a second reflow solder process is necessary, for temperature-sensitive components or to save electricity with the lower reflow temperature needed. The SB58-COSMO-NH-T4 SMD solder paste for dispensing convinces with it's highly precise contours, long open time, and consistent adhesiveness in the pick-and-place process. Its extremely good wetting properties, also on difficult surfaces, produce perfect soldering. Its extraordinarily consistent viscosity allows storage of up to 12 months which facilitates material planning. Due to its long shelf life and stability at room temperature, the paste is also ideal for rework with low consumption. Our SB58-COSMO-NH-T4 is vacuum degassed, which ensures uninterrupted dispensing in automated applications. Furthermore, solder paste can be transported without cooling. Cleaning after soldering is not necessary. The solder paste can be soldered under air or nitrogen reflow. The dispenser solder paste is available in 5cc, 10cc and 30cc cartridges.

Technical properties

	Specific value	Testing method
Alloy	Sn 42 / Bi 58	
Melting temperature range	138 - 138	IEC61189-11
Powder size (µm)	22 - 38, type 4	IPC-TM-650-2.2.14.2
Viscosity (Pa · s)	180 ± 30	IPC-TM-650-2.4.34.3
Flux content (wt %)	11 ± 0.5	IPC-TM-650-2.3.34.1
Flux type	ROL0, no clean	IPC-J-STD-004B
Printing pitch (mm)	0,4	
Halide content (%)	< 0.01	IPC-TM-650-2.3.35
Slump in heat (mm)	≤ 0,3	IPC-TM-650-2.4.35 (120°C / 60sec)
Insulation resistance (Ω)	≥ 1 x 10^{11} (40°C 90 % r. L)	IPC-TM-650-2.6.3.3
Insulation resistance (Ω)	≥ 5 x 10^{8} (85°C 85 % r. L)	IPC-TM-650-2.6.3.3
Migration test	No migration	IPC-TM-650-2.6.14.1
Copper mirror test	No corrosion	IPC-TM-650-2.3.32
Packaging	Cartridge 5cc, 10cc, 30cc	
Shelf life	12 months at 0-10°C, 3 months at < 25°C, 1 month at < 35°C	
Transport	Without cooling	

Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006.

Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental

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Protection Agency.

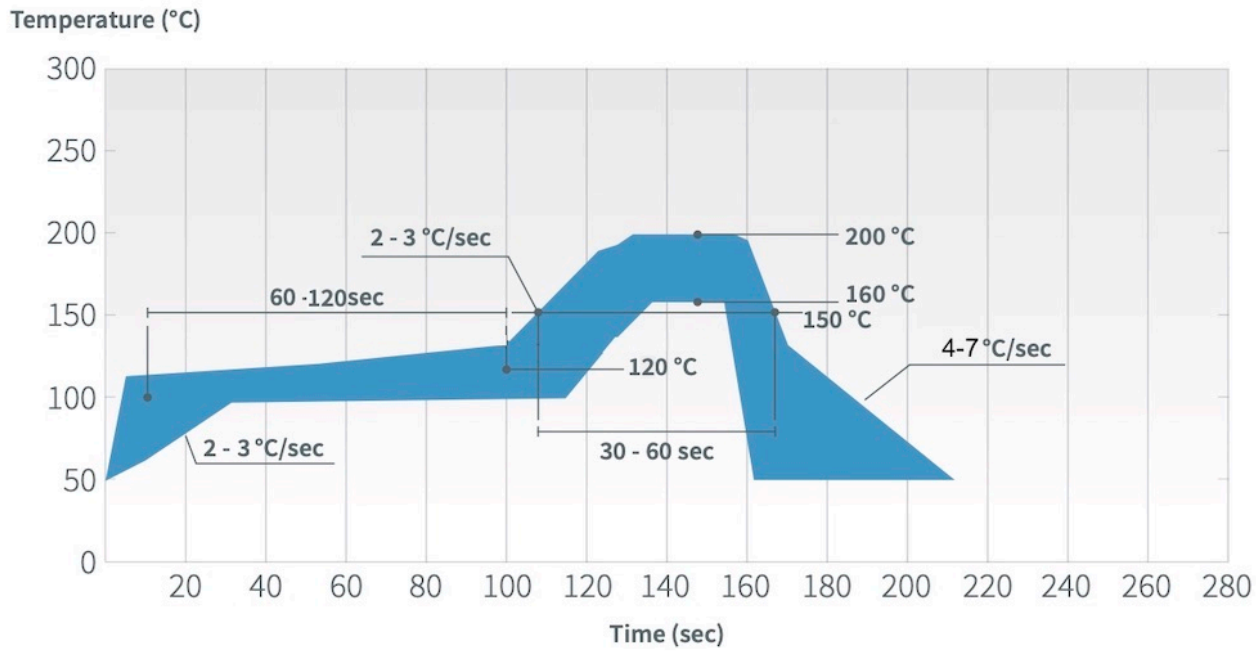
Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and PolyFuluoroAlkyl Substances (PFAS).

Contains no phthalates or latex.

Contains no substances according to California Proposition 65.

Recommended Reflow Profile



Preheating

The temperature increase should be 2°C to 3°C/sec until the preheating zone is reached. If the temperature rises too quickly this may cause a running of the solder paste.

To achieve a temperature spread (⊿t) on the circuit board that is as limited as possible, the temperature in the preheating zone should be between 120 and 150°C and the preheating time should be 60 to 120 seconds. If the temperature is too low or the preheating time too short, the temperature spread (⊿t) on the circuit board will be too high. If the temperature is too high and the preheating time too long the activators will get lost which may lead to poor melting of the solder paste.

Reflow peak

We recommend keeping the temperature at 160°C for 20 to 150 seconds.

Cooling down

The cooling rate should be between 4 and 7°C/sec. If the cooling rate is too low components may be displaced or come up and reduce the strength of the solder connections. If the cooling rate is too high, however, components can be damaged through thermal shock.